
2SK1628, 2SK1629

Silicon N-Channel MOS FET

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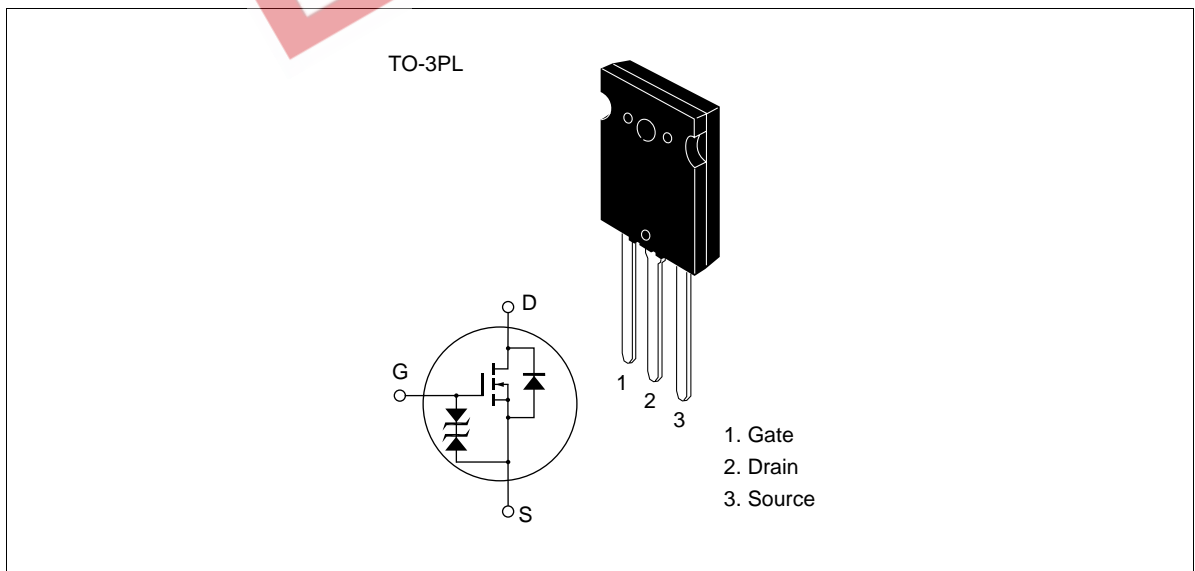
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

Outline



2SK1628, 2SK1629

Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1628	V_{DSS}	450	V
	2SK1629		500	
Gate to source voltage		V_{GSS}	±30	V
Drain current		I_D	30	A
Drain peak current		$I_{D(pulse)}^{*1}$	120	A
Body to drain diode reverse drain current		I_{DR}	30	A
Channel dissipation		Pch^{*2}	200	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

- Note
1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$
 2. Value at $T_c = 25^\circ C$

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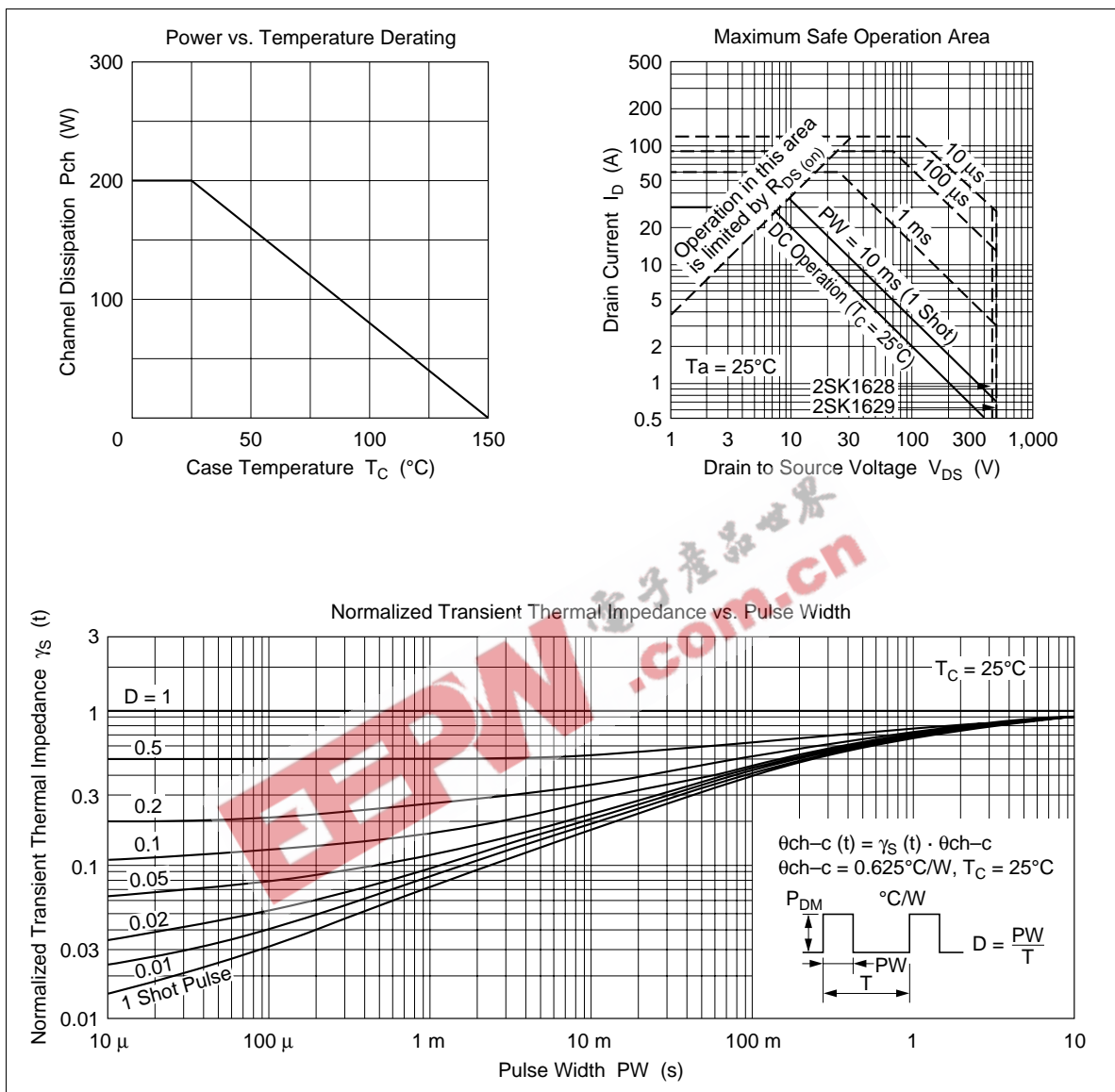
Electrical Characteristics (T_a = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	2SK1628 $V_{(BR)DSS}$ 2SK1629	450	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±30	—	—	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current	I_{GSS}	—	—	±10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	2SK1628 I_{DSS} 2SK1629	—	—	250	μA	$V_{DS} = 360 \text{ V}, V_{GS} = 0$ $V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	2.0	—	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source on state resistance	2SK1628 $R_{DS(on)}$ 2SK1629	—	0.20	0.25	Ω	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$ — 0.22 0.27
Forward transfer admittance	y _{fs}	12	20	—	S	$I_D = 15 \text{ A}, V_{DS} = 10 \text{ V}^{*1}$
Input capacitance	C _{iss}	—	2800	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance	C _{oss}	—	780	—	pF	$f = 1 \text{ MHz}$
Reverse transfer capacitance	C _{rss}	—	90	—	pF	
Turn-on delay time	t _{d(on)}	—	32	—	ns	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time	t _r	—	140	—	ns	$R_L = 2 \Omega$
Turn-off delay time	t _{d(off)}	—	200	—	ns	
Fall time	t _f	—	100	—	ns	
Body to drain diode forward voltage	V_{DF}	—	1.1	—	V	$I_F = 30 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	600	—	ns	$I_F = 30 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

Note 1. Pulse test

See characteristics curves of 2SK1169, 2SK1170

2SK1628, 2SK1629



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